

Attorney Docket No. 57761.000185

GE Docket: 03GP-8046

Serial Number: 09/683,496

Page 1 of 1

FORM PTO-1449
(REV. 7-80)U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.:
57761.000185SERIAL NO.:
09/683,496

LIST OF MATERIALS CITED BY APPLICANT

(Use several sheets if necessary)

INVENTOR'S NAME:
Eric LINDHOLM, et al.EXAMINER:
M. DatskovskyFILING DATE:
January 9, 2002GROUP
2835

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER							DATE	NAME	CLASS	SUB CLASS	FILING DATE
M. D.	A	6	0	1	8	4	5	9	01/25/00	Carlson, et al.			
M. D.	B	6	1	3	1	6	4	4	10/17/00	Kohara, et al.			
M. D.	C	6	1	3	1	6	5	0	10/17/00	North et al.			
M. D.	D	5	9	8	7	8	9	3	11/23/99	Schulz-Harder, et al.			
M. D.	E	6	0	1	4	3	1	2	01/11/00	Schulz-Harder et al.			
M. D.	F	5	8	4	1	6	3	4	11/24/98	Visser			
M. D.	G	5	2	0	5	3	5	3	04/27/93	Willemse, et al.			
	H												
	I												
	J												
	K												
	L												
	M												
	N												
	O												

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUB CLASS	TRANSLATION	
							YES	NO

OTHER MATERIALS (Including Author, Title, Date, Pertinent Pages, Etc.)

U.S. Patent Application 10/063,985, filed May 31, 2002 and the references cited therein.

"Fluid-Cooled DBC Substrates," by J. Schulz-Harder, K. Exel, and A. Meyer

"Direct Bond Copper Substrates," from Thermalloy

EXAMINER *M. Datskovsky* DATE CONSIDERED *06/08/04*

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.